

JFP WB300

Ultrasonics & Reflow Die Bonder



The machines which require minimal training to operate

MADE
IN FRANCE



Z Automated process



Click the following link to view the video <https://youtu.be/55NbtE87Q4I>

- **The WB300, a Die Bonder Equipment designed for accurate placement devices on substrate.**
- **Flip Chip Vision & Thermosonic bonding capabilities.**
- **Thermocompression & Eutectic capabilities.**
- **Reflow capability.**
- **Dispensing for glue or/and paste capability.**
- **High Magnification Optical Device for a high accuracy placement.**
- **Pick and Place of Dies under Vacuum with single collet.**
- **External Vibration Free.**

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DIE & SUBSTRATE

- Minimum die size 70*70µm
- Maximum die size 15*15 mm

VISION SYSTEM

- Video Microscope UHD cameras, 5Mp
Offset : field area, adjustable
- **Full std** FOV = 14,7mm,
- Digital Zoom , UHD Display Monitor
- Monitor : TFT 22"
- Led Lighting , co-axial and oblique
- Direct placement of Face-up devices

XY TABLE

- Vibration free
- Motion control with micrometer XY
- Compatible for any package up to 100 mm Thick.
- Fine rotary stage for precise alignment
- Placement accuracy <+/-5 µm.
Depending process

PARAMETERS

- PC Interface, GUI Menu
- Additional Force
- Programmable bond time and Power for ultrasonic process
- Flip Chip Alignment on/off
- Programmable temperature ramp-up

OPTIONAL Configuration

- Dispenser
- Additional Force : up to 5 or 12 kg
- Ultrasonic head
- Eutectic head
- Temperature up to 400°C
- Eutectic workholder
- Temperature up to 450°C
- Reflow workholder
- Temperature up to 250°C or 350°C
- Formic Acid Process
- Flip Face down camera
- Scrubbing Y
- Top cover for protective atmosphere

VIDEO MODE

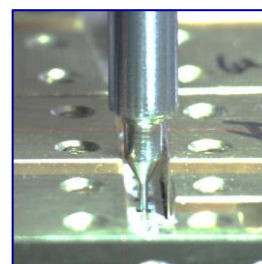


Video

Operator uses the vertical vision to precisely center the chips.
A powerful digital zoom & a fine focusing capability.
Crosshairs software.

Option Process Camera

Very useful to check the wire during Bond and Loop.
Side camera Picture is always at 'focus' distance.



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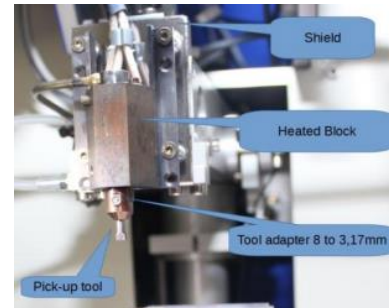
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OPTIONS

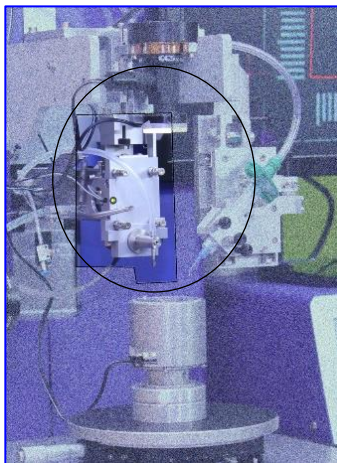
Eutectic head with controller

Compatible from room temperature up to 400°C

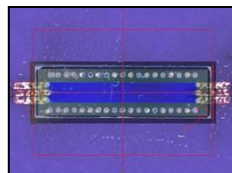
- Control of cycle Temperature profile :
- 3 programmable ramp-up
- Temperature Ramp-up: >4K/s
- heated block cooling
- low voltage supply: 48v , 350w
- Design large chip application
- Shank of 8mm, for very large chip



Ultrasonic head



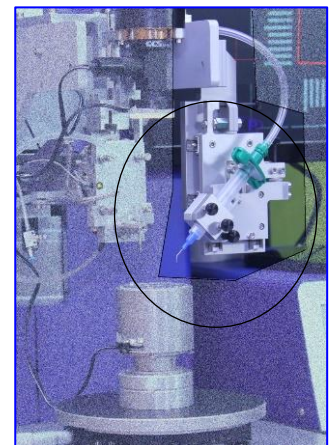
Flip System



Overlay Pictures

Dispensing head for Epoxy & Solder paste

- Manual dispenser, foot switch
- Dispense by Pressure / Time
- Seringue 3CC or 5 CC



Heated Workholder-Reflow with cover

- HP-60 Heated Workholder 60mm diameter
- HP-100 Heated Workholder 100 x 100 mm
- HP-150 Heated Workholder 150 x 100 mm
- HP-200 Heated Workholder 200 x 150 mm



HP-100



HP60

Technical Specifications

Electrical Requirements	100 / 240V , 50-60Hz
Current	max. 5A
Dimensions	640x710x550mm, (23"x21"x19")
Weight	60 kg

Software Interface-Touch Screen 7"

